503183379 02/18/2015

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ATAPOL PRAJUCKAMOL	02/16/2015
CHEE HIONG CHEW	02/16/2015
YUSHUANG YAO	02/16/2015

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC	
Street Address:	5005 E. MCDOWELL RD.	
Internal Address:	A700	
City:	PHOENIX	
State/Country:	ARIZONA	
Postal Code:	85008	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	29517863

CORRESPONDENCE DATA

Fax Number: (602)244-3169

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

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SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC **Correspondent Name:**

5005 E. MCDOWELL ROAD, MAILDROP A700 Address Line 1:

Address Line 4: PHOENIX, ARIZONA 85008

NAME OF SUBMITTER:	BECKY NEWNAM	
SIGNATURE:	/Becky Newnam/	
DATE SIGNED:	02/18/2015	

Total Attachments: 2

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> **PATENT REEL: 034977 FRAME: 0729** 503183379

ASSIGNMENT & AGREEMENT

ONS01685

For good and valuable consideration, the receipt of which is hereby acknowledged, we,

Name	of (City and State/Country)	
Atapol Prajuckamol	Klaeng, Rayong Thailand	
Chee Hiong Chew	Seremban, N.S. Malaysia	
Yushuang Yao	Seremban, N.S., Malaysia	

have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto Semiconductor Components Industries, LLC (SCI), a limited liability Company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain inventions relating to improvements in

POWER DEVICE PACKAGE

Attorney Docket No. ONS01685

described, illustrated, and claimed in an application for Letters Patent of the United States of America executed by us, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation, or reissue thereof.

We hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI.

We agree that, when requested, we will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.

We covenant with SCI, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

PATENT REEL: 034977 FRAME: 0730

ASSIGNMENT & AGREEMENT ONSO1685

and the second s
By (inventor signature):
Chee Hiong Chew
Witnessed by (Witness signature):
Printed name of Witness: AZHAR ARIPIN
Signed and Witnessed on (date): 16 Fe b 2015
By (Inventor signature):
Atapol Prajuckamol V
Witnessed by (Witness signature):
Printed name of Witness:AD-HAR HRIPIN
Signed and Witnessed on (date):
By (Inventor signature):
Yushuang Yao
Witnessed by (Witness signature):
Printed name of Witness: A HAR AR PON
Signed and Witnessed on (date):

PATENT REEL: 034977 FRAME: 0731

RECORDED: 02/18/2015